ALPHA & OMEGA SEMICONDUCTOR

AO4423/AO4423L

30V P-Channel MOSFET

General Description

The AO4423/AO4423L uses advanced trench technology to provide excellent $R_{DS(ON)}$, and ultra-low low gate charge with a 25V gate rating. This device is suitable for use as a load switch or in PWM applications.

* RoHS and Halogen-Free Compliant

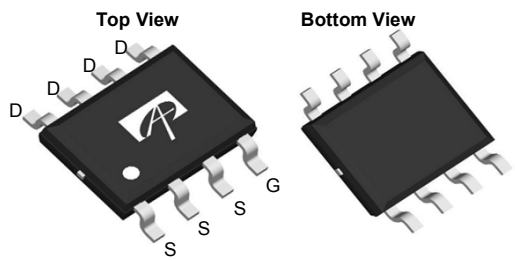
Product Summary

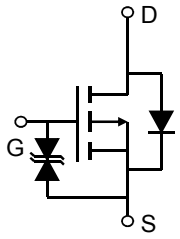
V_{DS} (V) = -30V
I_D = -17A (V_{GS} = -20V)
$R_{DS(ON)}$ < 6.2mΩ (V_{GS} = -20V)
$R_{DS(ON)}$ < 7.2mΩ (V_{GS} = -10V)

ESD Protected
100% UIS tested
100% Rg tested (note *)

Green Product

SOIC-8





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	±25	V
Continuous Drain Current [AF]	T_A=25°C	I_D	-17	A
	T_A=70°C		-14	
Pulsed Drain Current [B]		I_{DM}	-182	
Power Dissipation [A]	T_A=25°C	P_D	3.1	W
	T_A=70°C		2	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [AF]	t ≤ 10s	$R_{\theta JA}$	26	40	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		50	75	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	14	24	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=-250µA, V_{GS}=0V	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-30V, V_{GS}=0V			-1	µA
		T_J=55°C			-5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±1	µA
		V_{DS}=0V, V_{GS}=±25V			±10	µA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=-250µA	-1.5	-2.1	-2.6	V
$I_{D(ON)}$	On state drain current	V_{GS}=-10V, V_{DS}=-5V	-182			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-20V, I_D=-15A		5.1	6.2	mΩ
		T_J=125°C		7.4	9	
		V_{GS}=-10V, I_D=-15A		5.9	7.2	mΩ
		V_{GS}=-6V, I_D=-10A		7.5	9.5	mΩ
g_{FS}	Forward Transconductance	V_{DS}=-5V, I_D=-15A		48		S
V_{SD}	Diode Forward Voltage	I_S=-1A,V_{GS}=0V		-0.71	-1	V
I_S	Maximum Body-Diode Continuous Current				-4.2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-15V, f=1MHz		2527	3033	pF
C_{oss}	Output Capacitance			583		pF
C_{rss}	Reverse Transfer Capacitance			397	556	pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	2.1	4.3	6.4	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	V_{GS}=-10V, V_{DS}=-15V, I_D=-15A		47	57	nC
Q_{gs}	Gate Source Charge			8		nC
Q_{gd}	Gate Drain Charge			14		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=-10V, V_{DS}=-15V, R_L=1.0Ω, R_{GEN}=3Ω		12		ns
t_r	Turn-On Rise Time			8		ns
$t_{D(off)}$	Turn-Off DelayTime			54		ns
t_f	Turn-Off Fall Time			87		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=-15A, dI/dt=100A/µs		26.1	32	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-15A, dI/dt=100A/µs		12.3		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design.
B: Repetitive rating, pulse width limited by junction temperature.
C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.
D. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.
E. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The SOA curve provides a single pulse rating.
F. The current rating is based on the t≤ 10s junction to ambient thermal resistance rating.
Note *: This device is guaranteed RG 100% tested after date code 8V11 (Jan 1st 2008)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

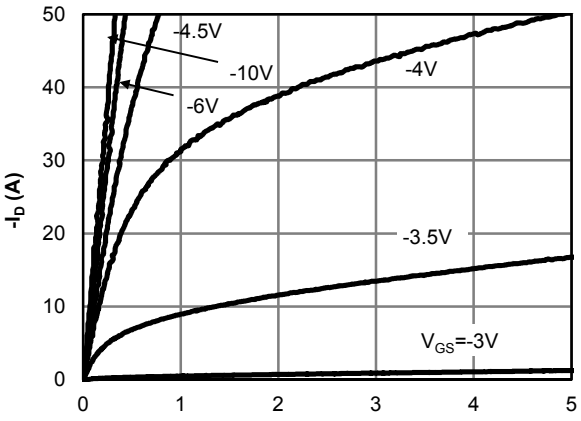


Fig 1: On-Region Characteristics

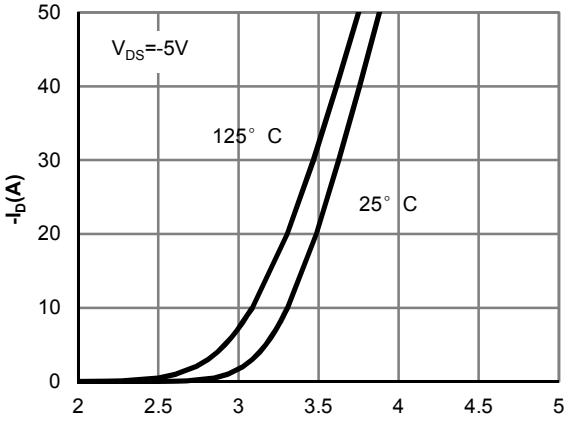


Figure 2: Transfer Characteristics

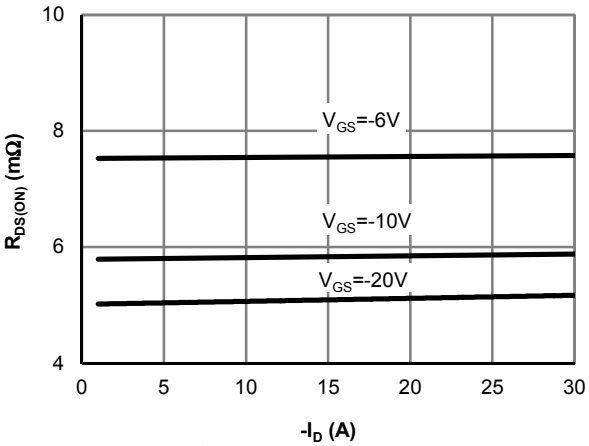


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

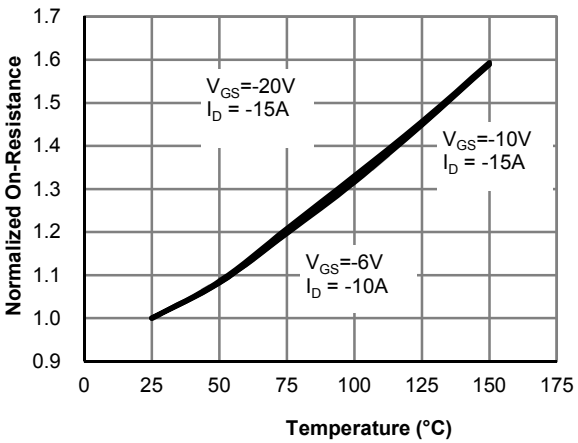


Figure 4: On-Resistance vs. Junction Temperature

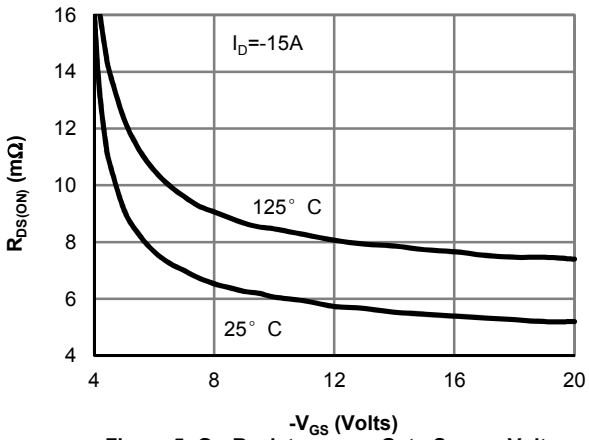


Figure 5: On-Resistance vs. Gate-Source Voltage

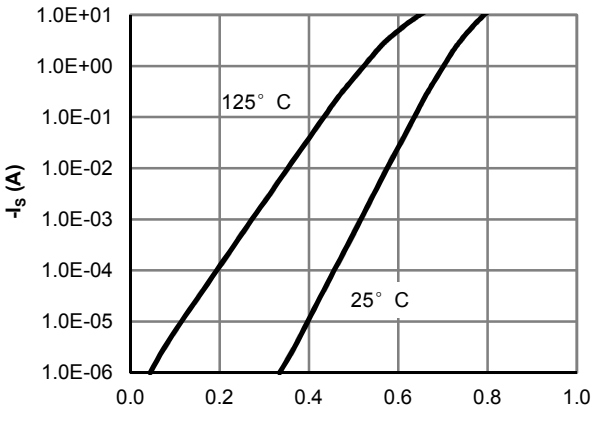


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

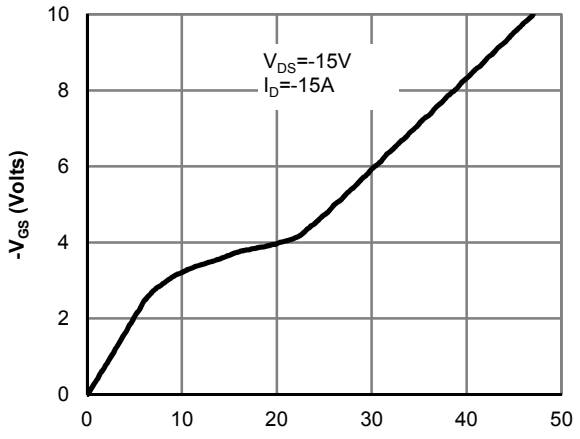


Figure 7: Gate-Charge Characteristics

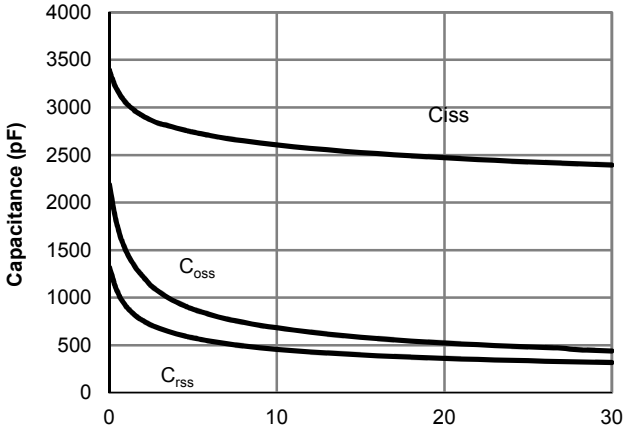


Figure 8: Capacitance Characteristics

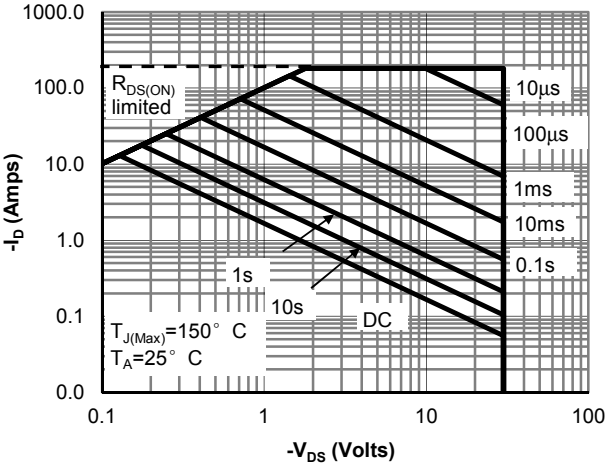


Figure 9: Maximum Forward Biased Safe

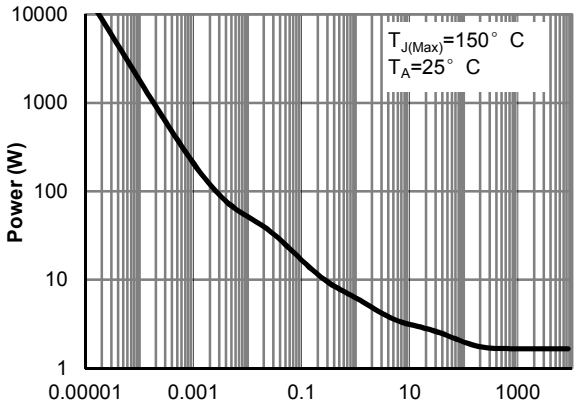


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

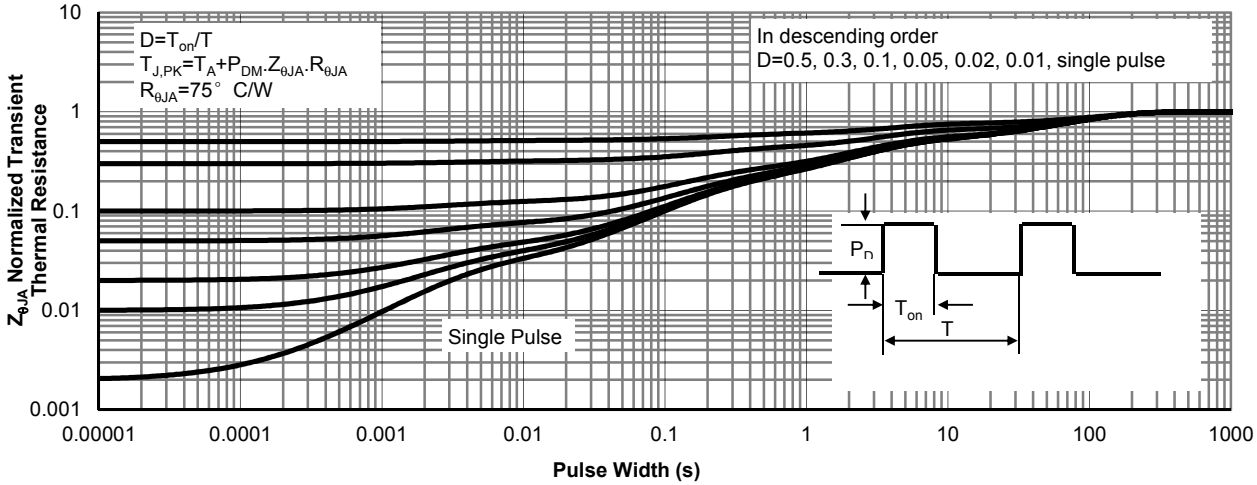
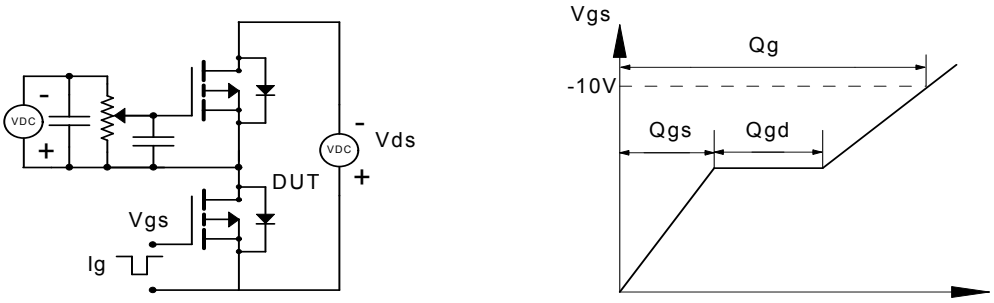
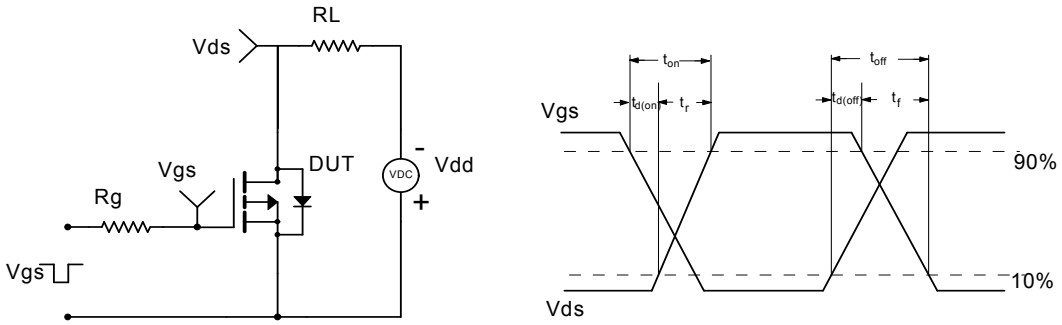


Figure 11: Normalized Maximum Transient Thermal Impedance

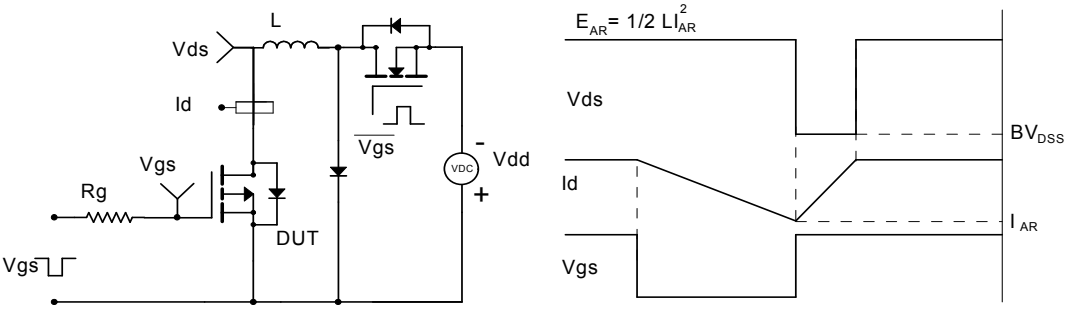
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms